



## UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
 United States Patent and Trademark Office  
 Address: COMMISSIONER FOR PATENTS  
 P.O. Box 1450  
 Alexandria, Virginia 22313-1450  
 www.uspto.gov

## \*BIBDATASHEET\*

Bib Data Sheet

CONFIRMATION NO. 3830

SERIAL NUMBER 09/991,166	FILING DATE 11/16/2001  RULE	CLASS 438	GROUP ART UNIT 1765	ATTORNEY DOCKET NO. 05630 USA P 01/ETCH/METAL
-----------------------------	---------------------------------------	--------------	------------------------	--

## APPLICANTS

Chentsau Ying, Cupertino, CA;

Jeng H. Hwang, Cupertino, CA;

Yong Deuk Ko, Kyonggi, KOREA, REPUBLIC OF; Se Jin Oh, Suwon, KOREA, REPUBLIC OF;  
 Chan Ouk Jung, Seoul, KOREA, REPUBLIC OF;

## \*\* CONTINUING DATA \*\*\*\*\*

verified LV

This application is a CIP of 09/918,671 07/27/2001 PAT 6,770,567

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

YOR LV

REPUBLIC OF KOREA 10-2001-40309 07/06/2001

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 12/03/2001

Foreign Priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY CA	SHEETS DRAWING 6	TOTAL CLAIMS 60	INDEPENDENT CLAIMS 7
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	Verified and Acknowledged	Examiner's Signature <i>LV</i>	Initials LV	

## ADDRESS

32588  
 APPLIED MATERIALS, INC.  
 2881 SCOTT BLVD. M/S 2061  
 SANTA CLARA, CA  
 95050

## TITLE

Method of reducing particulates in a plasma etch chamber during a metal etch process

FILING FEE	FEES: Authority has been given in Paper	<input type="checkbox"/> All Fees
		<input type="checkbox"/> 1.16 Fees ( Filing )